

Description

The AP20P02SI uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = -20V I_{D} = -20A$

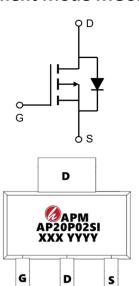
 $R_{DS(ON)} < 38m\Omega @ V_{GS}=-4.5V (Type: 32m\Omega)$

Application

Battery protection

Load switch

Uninterruptible power supply





Package Marking and Ordering Information

| · achago marki | actuage marking and cracing information | | | | |
|----------------|---|--------------------|----------|--|--|
| Product ID | Pack | Marking | Qty(PCS) | | |
| AP20P02SI | SOT89-3L | AP20P02SI XXX YYYY | 1000 | | |

Absolute Maximum Ratings (T_c=25 ℃ unless otherwise noted)

| Symbol | Parameter | Rating | Units |
|--------------------------------------|---|------------------|------------|
| V _{DS} | Drain-Source Voltage -20 | | V |
| V _G s | Gate-Source Voltage ±12 | | V |
| I ∂ @T _A =25°C | Continuous Drain Current, V _{GS} @ -4.5V ¹ -20 | | А |
| I _D @T _A =70℃ | Continuous Drain Current, V _{GS} @ -4.5V ¹ -5.9 | | А |
| Ірм | Pulsed Drain Current ² -60 | | А |
| P _D @T _A =25℃ | Total Power Dissipation ³ 431 | | W |
| P _D @T _A =70°C | Total Power Dissipation ³ 0.84 | | W |
| T _{STG} | Storage Temperature Range -55 to 150 | | $^{\circ}$ |
| TJ | Operating Junction Temperature Range | nge -55 to 150 ℃ | |
| R₀JA | Thermal Resistance Junction-Ambient ¹ | 250 °C/W | |
| RθJC | Thermal resistance, junction-case | 7.4 °C/W | |





Electrical Characteristics (T_J=25°C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|------------------------|---|--|------|--------|------|-----------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V , I _D =-250uA | -20 | | | V |
| △BVDSS/△TJ | BV _{DSS} Temperature Coefficient | Reference to 25 $^{\circ}\!$ | | -0.014 | | V/°C |
| | | V _{GS} =-4.5V , I _D =-4.9A | | 32 | 38 | |
| R _{DS(ON)} | Static Drain-Source On-Resistance ² | V_{GS} =-2.5V , I_D =-3.4A | | 45 | 55 | $m\Omega$ |
| | | V_{GS} =-1.8 V , I_{D} =-2 A | | 65 | 85 | |
| V _{GS(th)} | Gate Threshold Voltage | $V_{GS}=V_{DS}$, $I_D=-250uA$ | -0.4 | | -1.0 | V |
| $\triangle V_{GS(th)}$ | V _{GS(th)} Temperature Coefficient | VGS-VDS , ID2300A | | 3.95 | | mV/℃ |
| l | V _{DS} =-16V , V _{GS} =0V , T _J =2 | $V_{\text{DS}}\text{=-}16\text{V}$, $V_{\text{GS}}\text{=}0\text{V}$, $T_{\text{J}}\text{=}25^{\circ}\!$ | | | -1 | uA |
| I _{DSS} | Drain-Source Leakage Current V _{DS} =-16V , V _{GS} =0V , T _J =55°C | | | | -5 | uA |
| Igss | Gate-Source Leakage Current | V _{GS} =±12V , V _{DS} =0V | | | ±100 | nA |
| gfs | Forward Transconductance | V_{DS} =-5 V , I_{D} =-3 A | | 12.8 | | S |
| Q_g | Total Gate Charge (-4.5V) | | | 10.2 | 14.3 | |
| Qgs | Gate-Source Charge | V_{DS} =-15 V , V_{GS} =-4.5 V , I_{D} =-3 A | | 1.89 | 2.6 | nC |
| Q _{gd} | Gate-Drain Charge | | | 3.1 | 4.3 | |
| T _{d(on)} | Turn-On Delay Time | | | 5.6 | 11.2 | |
| Tr | Rise Time | V_{DD} =-10V , V_{GS} =-4.5V , | | 40.8 | 73 | |
| T _{d(off)} | Turn-Off Delay Time | $R_G=3.3$, $I_D=-3A$ | | 33.6 | 67 | ns |
| T _f | Fall Time | | | 18 | 36 | |
| Ciss | Input Capacitance | | | 857 | 1200 | |
| Coss | Output Capacitance | V_{DS} =-15V , V_{GS} =0V , f=1MHz | | 114 | 160 | F |
| Crss | Reverse Transfer Capacitance | | | 108 | 151 | pF |
| Is | Continuous Source Current ^{1,4} | \\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\ | | | -4.9 | Α |
| Ism | Pulsed Source Current ^{2,4} | $V_G=V_D=0V$, Force Current | | | -14 | Α |
| V _{SD} | Diode Forward Voltage ² | V _{GS} =0V , I _S =-1A , T _J =25℃ | | | -1 | V |
| t _{rr} | Reverse Recovery Time | IF=-3A , di/dt=100A/μs , | | 21.8 | | nS |
| Qrr | Reverse Recovery Charge | TJ=25°C | | 6.9 | | nC |

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2 $\,$ The data tested by pulsed , pulse width \triangle 300us , duty cycle \triangle 2%
- 4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

N



Typical Characteristics

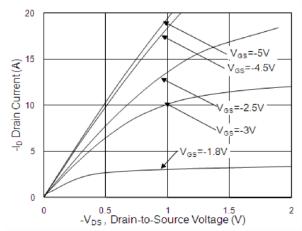


Fig.1 Typical Output Characteristics

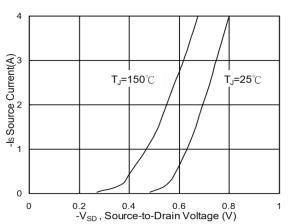


Fig.3 Forward Characteristics of Reverse

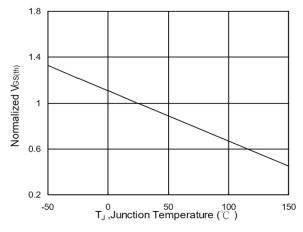


Fig.5 Normalized $V_{\text{GS(th)}}$ vs. T_{J}

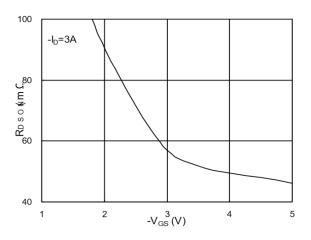


Fig.2 On-Resistance vs. G-S Voltage

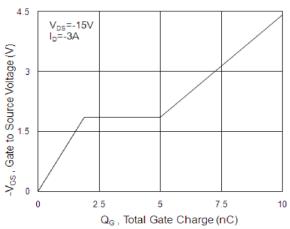


Fig.4 Gate-charge Characteristics

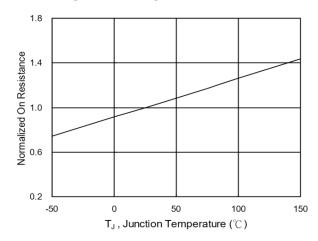
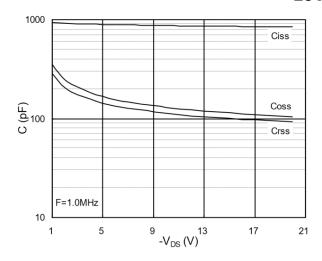


Fig.6 Normalized Roson vs. TJ







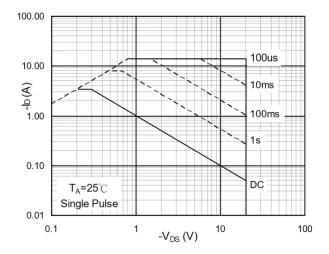


Fig.7 Capacitance

Fig.8 Safe Operating Area

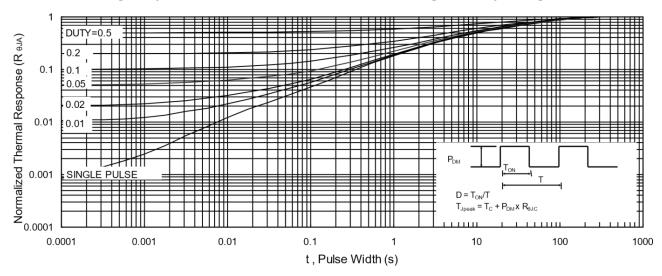
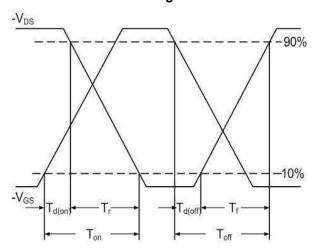


Fig.9 Normalized Maximum Transient Thermal Impedance



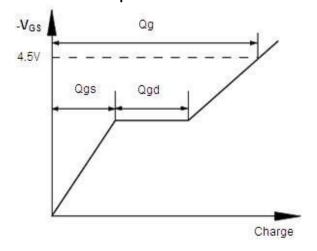


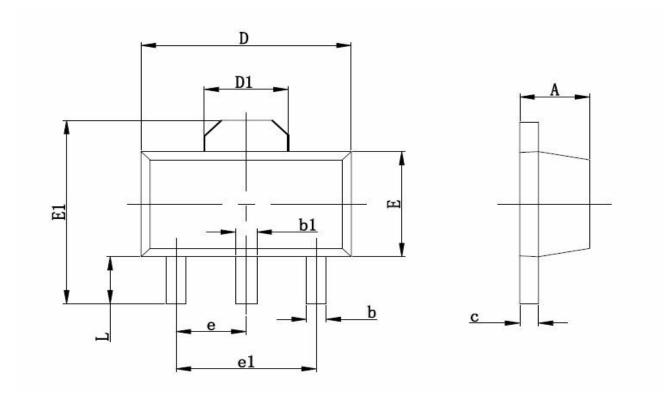
Fig.10 Switching Time Waveform

Fig.11 Gate Charge Waveform

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Package Mechanical Data:SOT89-3L



| Cumbal | Dimensions | In Millimeters | Dimension | s In Inches |
|--------|------------|----------------|-----------|-------------|
| Symbol | Min | Max | Min | Max |
| Α | 1.400 | 1.600 | 0.055 | 0.063 |
| b | 0.350 | 0.520 | 0.013 | 0.197 |
| b1 | 0.400 | 0.580 | 0.016 | 0.023 |
| С | 0.350 | 0.440 | 0.014 | 0.017 |
| D | 4.400 | 4.600 | 0.173 | 0.181 |
| D1 | 1.550 |) REF | 0.061 | REF |
| E | 2.350 | 2.550 | 0.091 | 0.102 |
| E1 | 3.940 | 4.250 | 0.155 | 0.167 |
| е | 1.500 |) TYP | 0.06 | 0TYP |
| e1 | 3.000 |) TYP | 0.11 | 8TYP |
| L | 0.900 | 1.100 | 0.035 | 0.047 |



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